

L Number	Hits	Search Text	DB	Time stamp
1	141	wafer adj support adj assembly	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 16:41
2	2	(wafer adj support adj assembly) same (ceramic adj puck)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 17:00
3	10	(wafer adj support adj assembly) same pedestal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 17:02
4	98870	chuck chucking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 16:59
5	5191	electrostatic adj chuck	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 17:00
6	4	(electrostatic adj chuck) same (ceramic adj puck)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 17:00
7	466	(electrostatic adj chuck) same pedestal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 17:02
8	1	((electrostatic adj chuck) same pedestal) same (thermal adj control adj plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 17:03
9	77	((electrostatic adj chuck) same pedestal) same base	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 17:04
10	3	((((electrostatic adj chuck) same pedestal) same base) same brazed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 17:04